

Semiconductor Sensors:

Ch6: Gas Sensors cont.

Work Function Effect Gas Sensors

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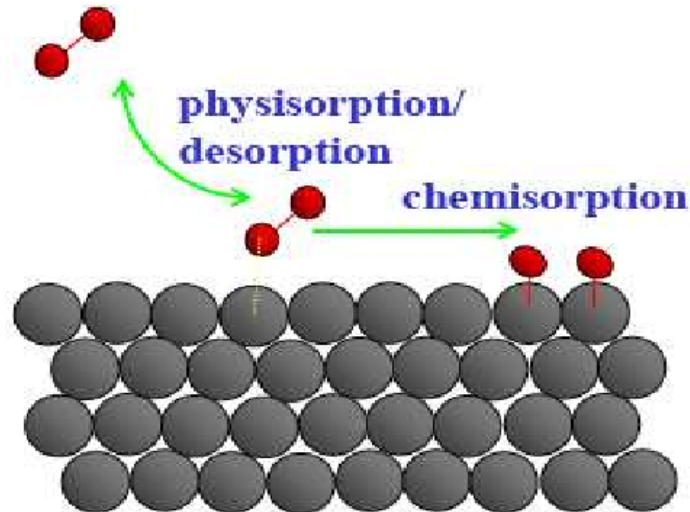
Assistant Professor of Electrical Engineering

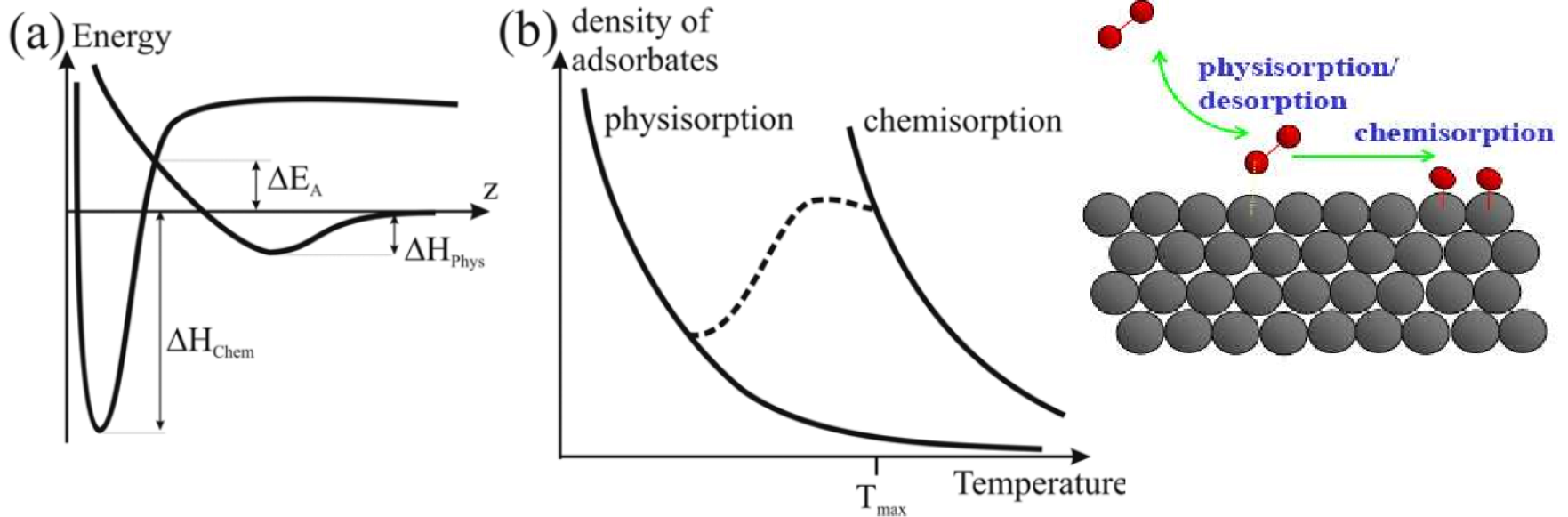
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Fig. 3 Gas adsorption on a solid: physisorption (*left*) and chemisorption (*right*)

Fleischer, M., & Lehmann, M. (Eds.). (2012). Solid State Gas Sensors-Industrial Application (Vol. 11). Springer Science & Business Media.





(a) Lenard-Jones model for physisorption and chemisorption of molecules. Typical adsorption isobars are shown in (b). The solid lines are equilibrium physisorption and chemisorption isobars, the dashed line represents irreversible chemisorption. A maximum coverage of chemisorbed molecules is obtained at T_{max} .

ΔE_A is the activation barrier for chemisorption and ΔH_{chemis} the heat of chemisorption. Under steady state conditions

In case of dissociative chemisorption, the molecular coverage Θ_x is calculated from a simple rate equation, as displayed in Fig. 4.

$$\frac{d\Theta_x}{dt} = 2p_x k_a (1 - \Theta_x)^2 - 2k_d \Theta_x^2$$

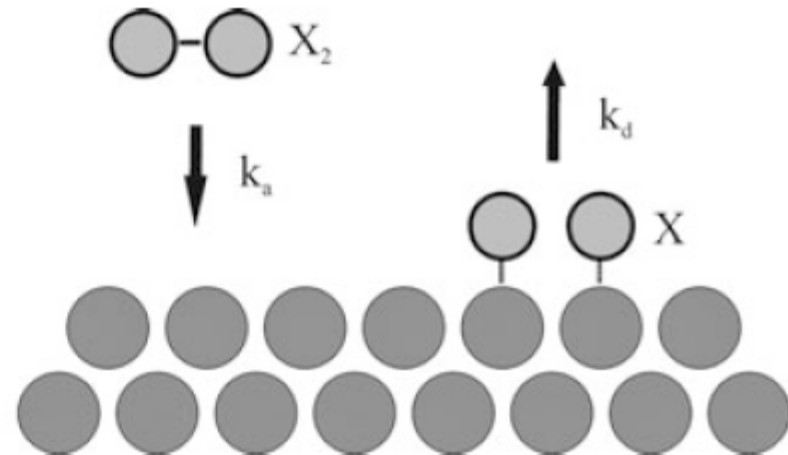


Fig. 4 Rate equation (*left*) and schematic view of dissociative adsorption and desorption (*right*)

p_x is the partial pressure; $k_{a/d}$ are rate constants for adsorption and desorption.

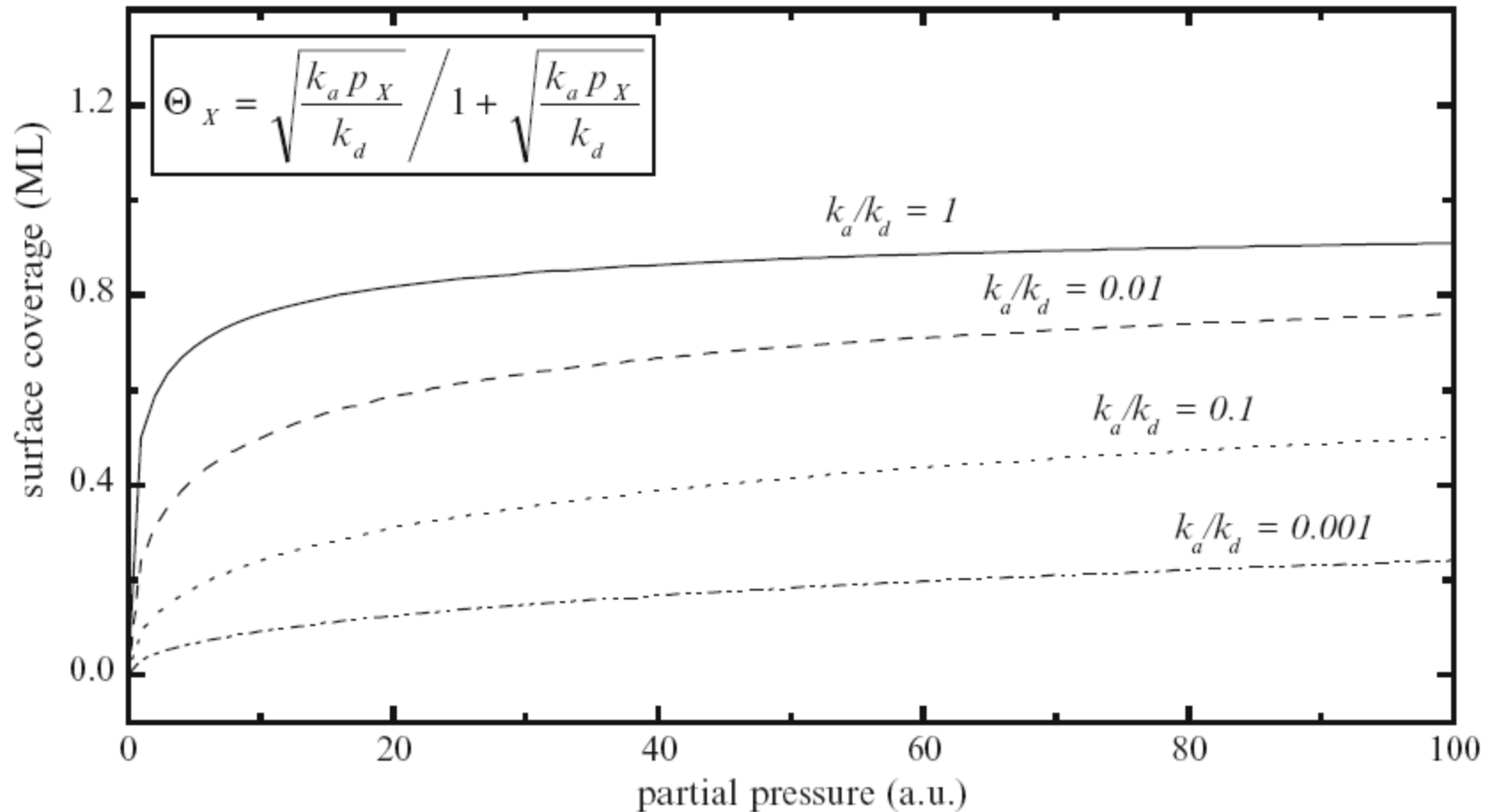


Fig. 5 Surface coverage equation (*inset*) and graphical solution of dissociative adsorption and desorption with respect to partial pressure

Work Function for various elements (eV)

تابع کار مواد مختلف

Element	eV	Element	eV	Element	eV	Element	eV	Element	eV
Ag:	4.52-4.74	Al:	4.06-4.26	As:	3.75	Au:	5.1-5.47	B:	~4.45
Ba:	2.52-2.7	Be:	4.98	Bi:	4.34	C:	~5	Ca:	2.87
Cd:	4.08	Ce:	2.9	Co:	5	Cr:	4.5	Cs:	2.14
Cu:	4.53-5.10	Eu:	2.5	Fe:	4.67-4.81	Ga:	4.32	Gd:	2.90
Hf:	3.9	Hg:	4.475	In:	4.09	Ir:	5.00-5.67	K:	2.29
La:	3.5	Li:	2.93	Lu:	~3.3	Mg:	3.66	Mn:	4.1
Mo:	4.36-4.95	Na:	2.36	Nb:	3.95-4.87	Nd:	3.2	Ni:	5.04-5.35
Os:	5.93	Pb:	4.25	Pd:	5.22-5.6	Pt:	5.12-5.93	Rb:	2.261
Re:	4.72	Rh:	4.98	Ru:	4.71	Sb:	4.55-4.7	Sc:	3.5
Se:	5.9	Si:	4.60-4.85	Sm:	2.7	Sn:	4.42	Sr:	~2.59
Ta:	4.00-4.80	Tb:	3.00	Te:	4.95	Th:	3.4	Ti:	4.33
Tl:	~3.84	U:	3.63-3.90	V:	4.3	W:	4.32-5.22	Y:	3.1
Zn:	3.63-4.9	Zr:	4.05						

The **work function** is defined as the minimum energy, which is necessary to extract an electron from a neutral solid.

Al	Fermi Level (eV)	Vacuum (eV)	Work Function (eV)	Experimental (eV)
(100)	2.364	6.782	4.418	4.41 ± 0.02
(110)	2.488	6.768	4.28	4.28 ± 0.02
(111)	2.634	6.869	4.235	4.24 ± 0.03

Table 1: Calculations of work functions of Aluminum, showing that work function is dependent on the type of surface

Cu	Fermi Level (eV)	Vacuum (eV)	Work Function (eV)	Experimental (eV)
(100)	5.551	10.391	4.84	4.59 ± 0.03
(110)	2.390	7.105	4.715	4.48 ± 0.03
(111)	5.581	10.780	5.199	4.94 ± 0.03

Table 2: Calculations of work functions of different surfaces of Cu.

Work Function Change Caused by Gas Adsorption

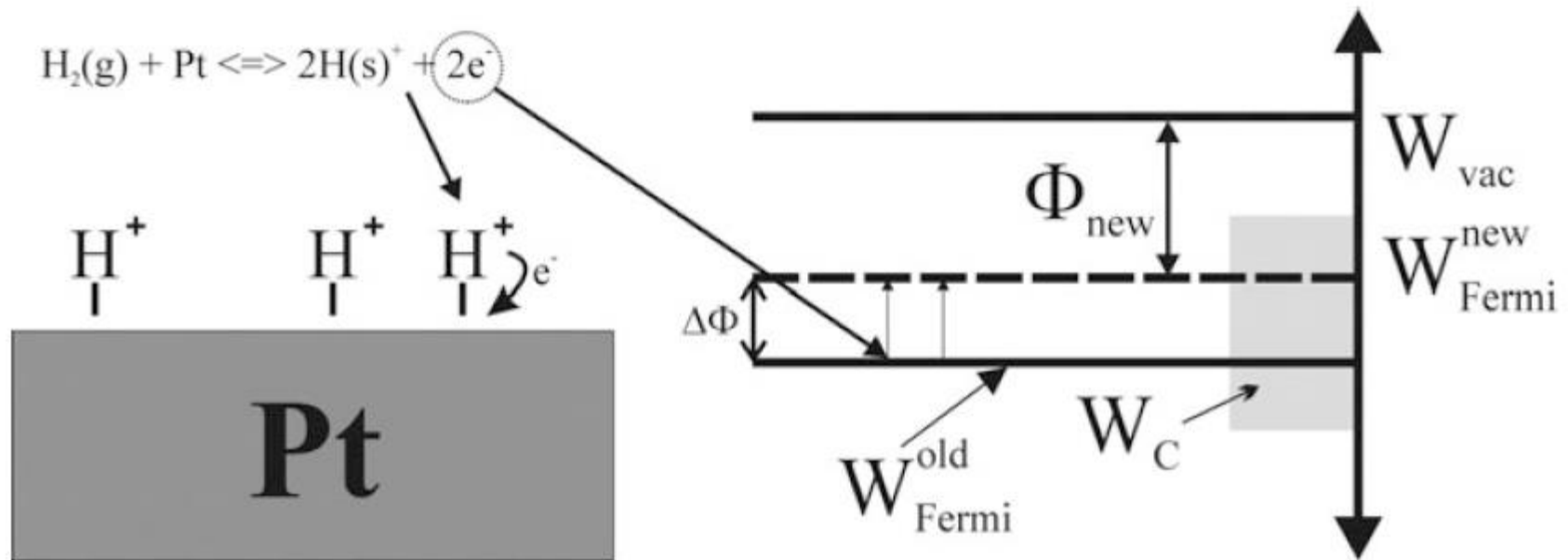


Fig. 7 Work function change caused by chemisorption of hydrogen on clean platinum

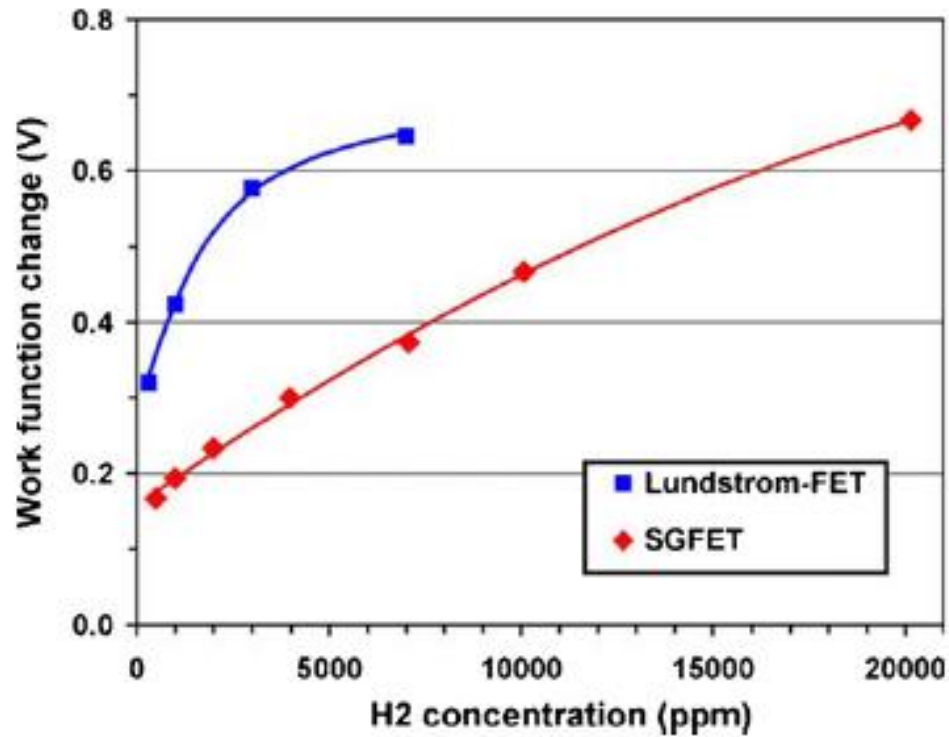
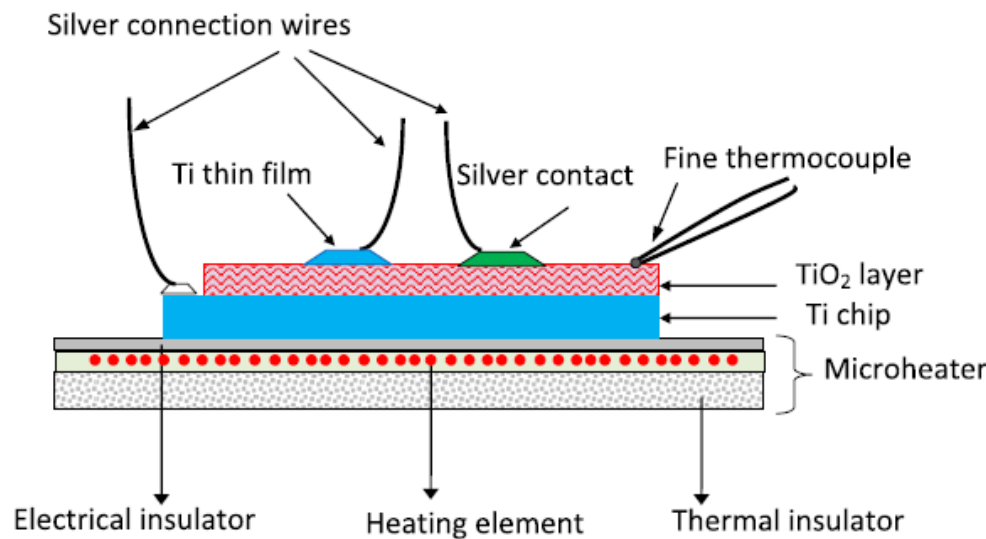
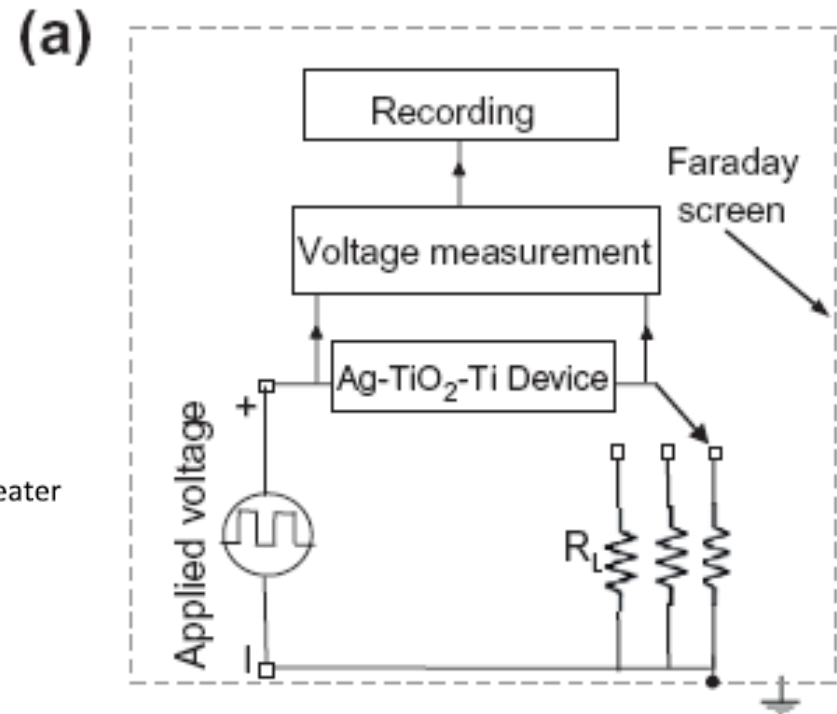


Fig. 36. Hydrogen sensitivity of Lundstrom-FET and SG-FET with Pt gate at low H₂ concentrations. From [98].

اثر: تغییر تابع کار فلز و ارتفاع سطح شاتکی با گاز.



The schematic diagram of the Ti-TiO₂ and Ag-TiO₂ junctions fabricated on a thermally oxidized titanium metal chip mounted on a microheater.



The experimental setup used for the measurement of the I-V characteristics of the forward biased Ag-TiO₂ diode

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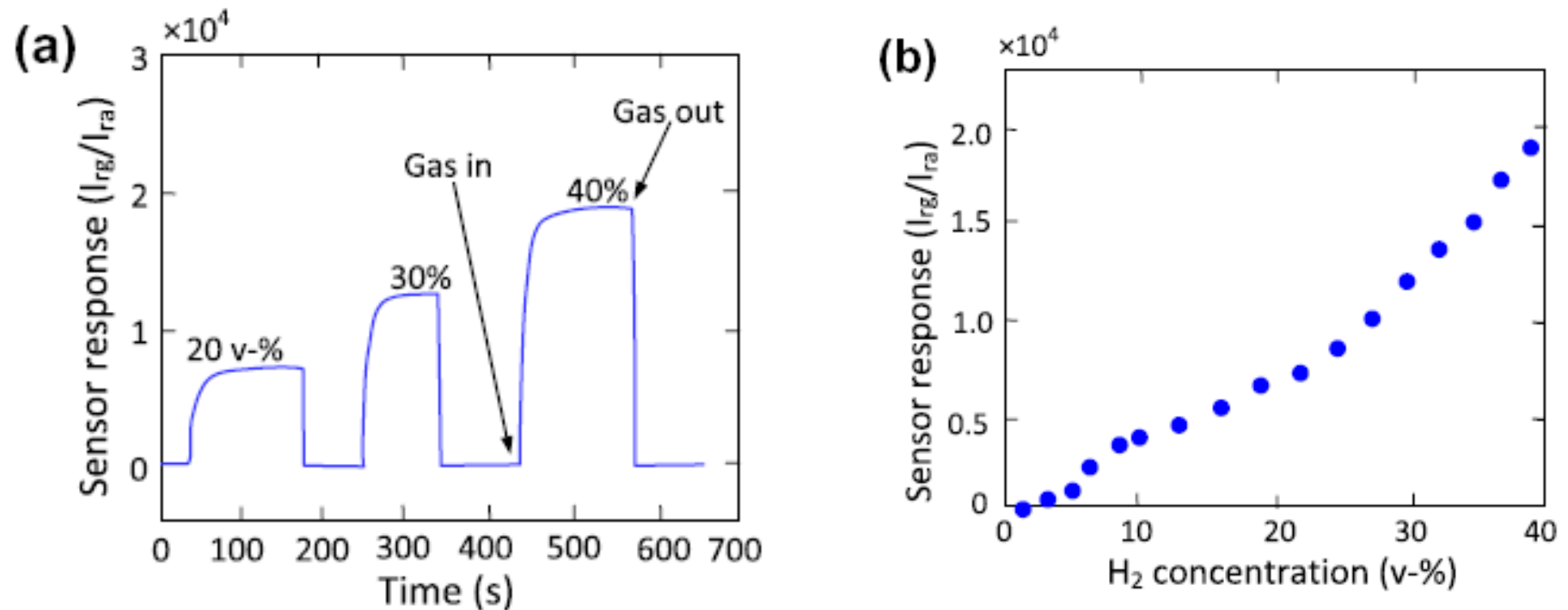


Fig. 7. The transient (a) and the steady state (b) responses of the Ag-TiO₂ sensor operating at 300 °C to different concentration levels of H₂ in air.

where I_{rg} and I_{ra} are the reverse currents measured at the contaminated air and clean air, respectively.

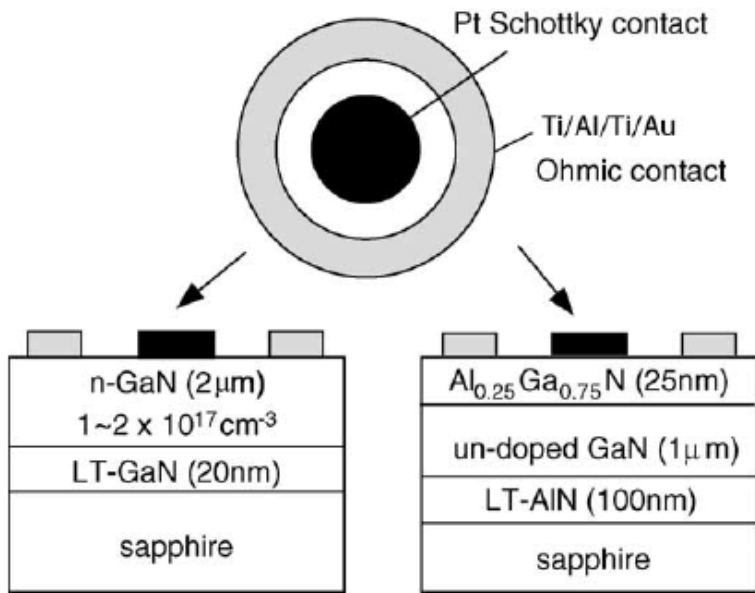


Fig. 1. Structures of Pt/GaN and Pt/AlGaIn/GaN Schottky diodes used in this study.

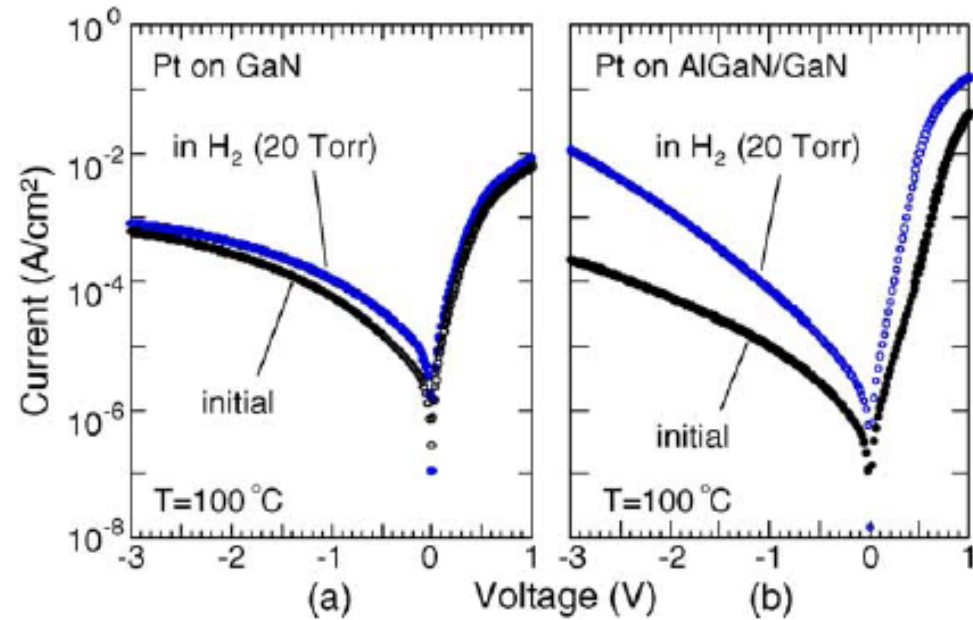


Fig. 2. Typical I - V characteristics of (a) Pt/GaN and (b) Pt/AlGaIn/GaN Schottky diodes before and after exposure to H_2 at $100\text{ }^\circ\text{C}$.

Observed current changes are due to changes in Schottky barrier heights (SBH). Such a change of SBH can be either due to H-induced formation of interfacial dipole, or to hydrogen passivation of interface states causing Fermi level pinning at the Schottky interface.

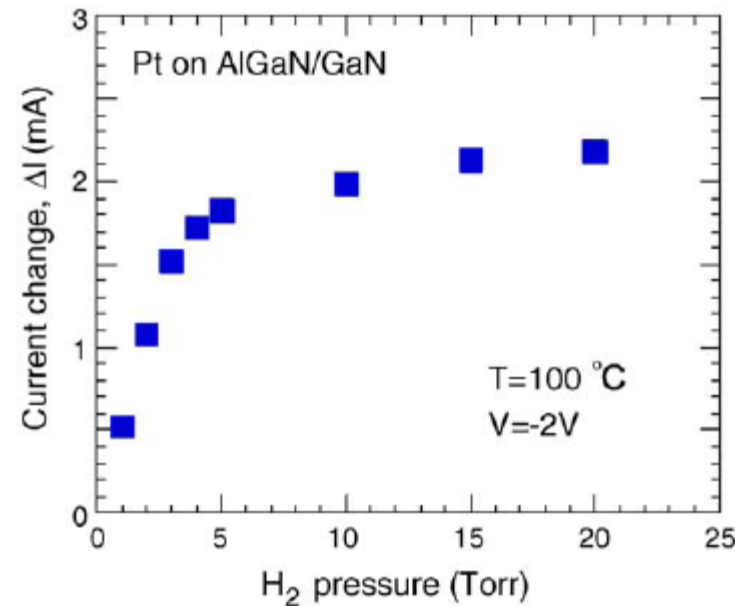
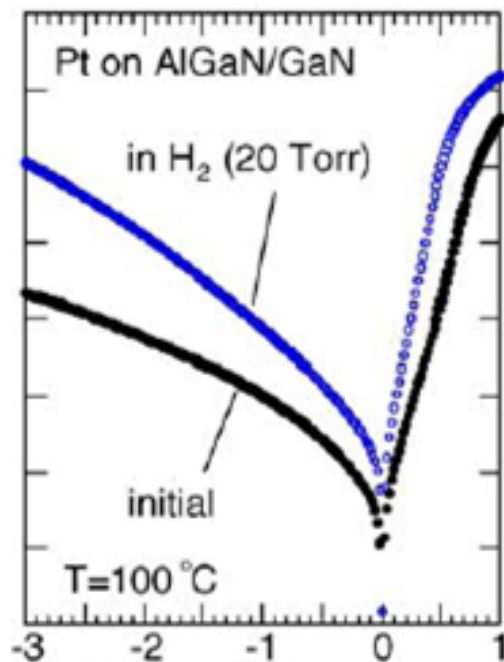


Fig. 3. Current change, ΔI , at $V = -2$ V at 100 °C as a function of H_2 pressure for a Pt/AlGaIn/GaN Schottky diode.

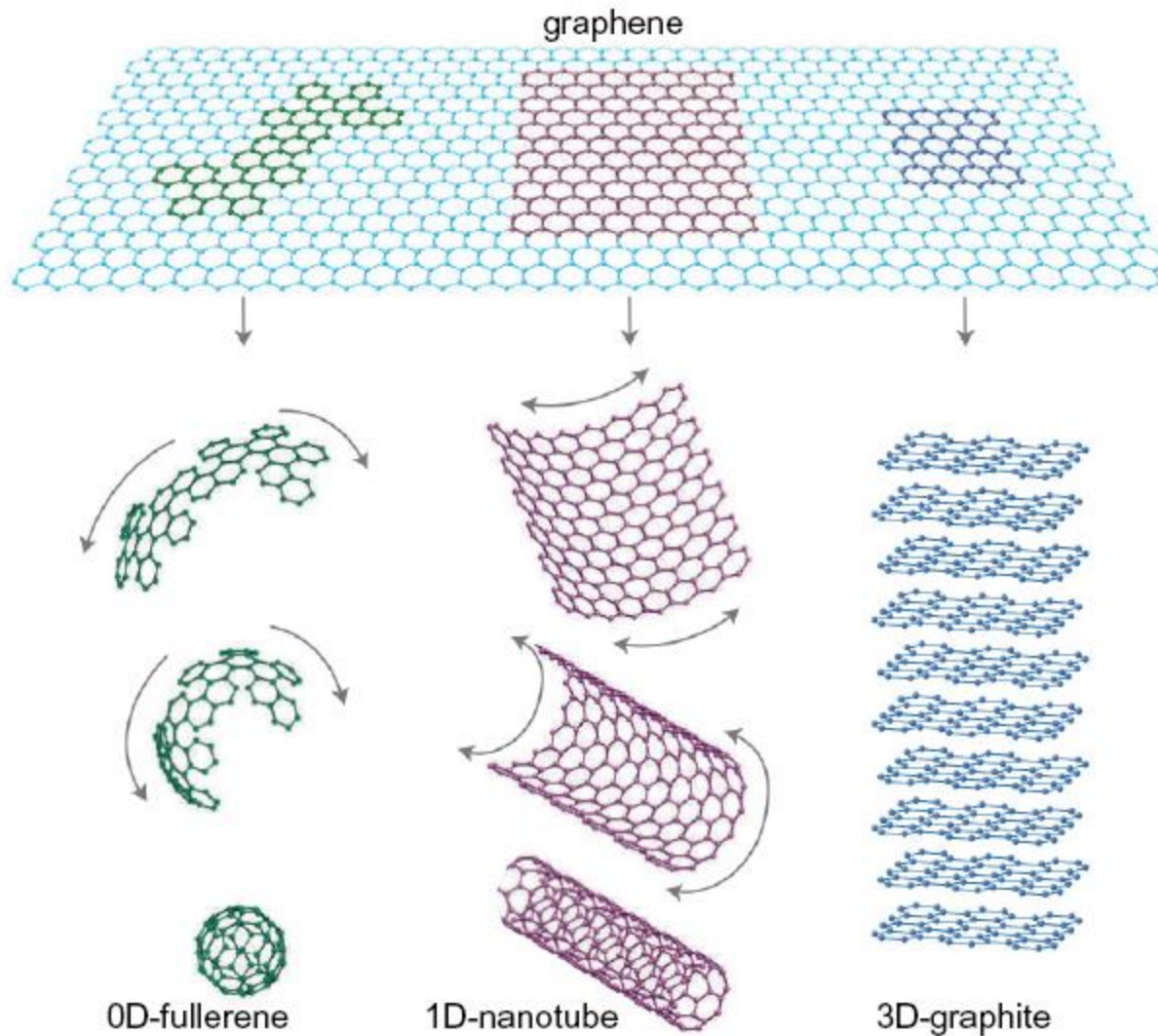


Table 14.2 Examples of Carbon Electronic Gas Sensors

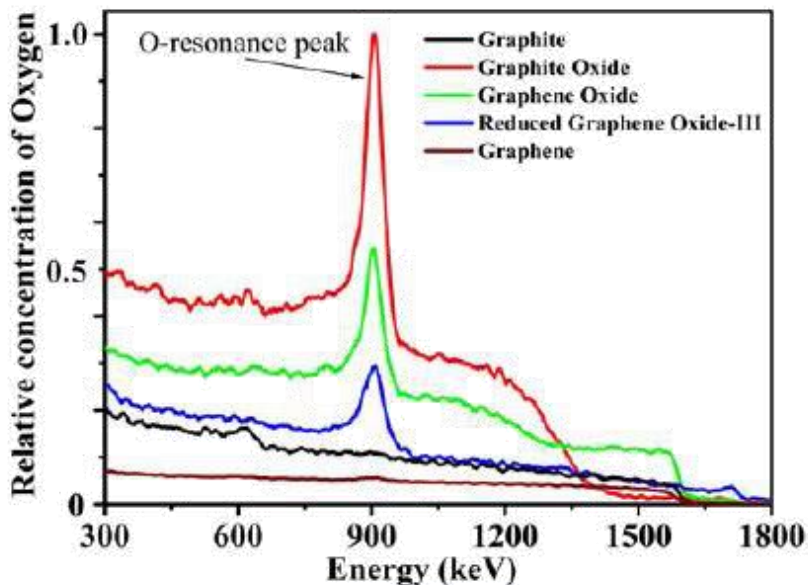
Material and Device	Gases Detected	Sensitivity
SWCNT field-effect transistor (FET)	NO ₂	~2 ppm
SWCNT FET	NH ₃	~0.1%
CNT films on resonator	NH ₃	~100 ppm
SWCNT network FET	Dimethyl methylphosphonate	Sub-ppb
PEI-coated multiple-SWCNT FET	NO ₂	<1 ppb
Nafion-coated multiple-SWCNT FET	NH ₃	<100 ppm
SWCNT network resistor	NO ₂	44 ppb
SWCNT network resistor	Nitrotoluene	262 ppb
Carbon black/polymer composite	Dimethyl methylphosphonate	~9–46 ppb
CNF film	NO ₂	10 ppb

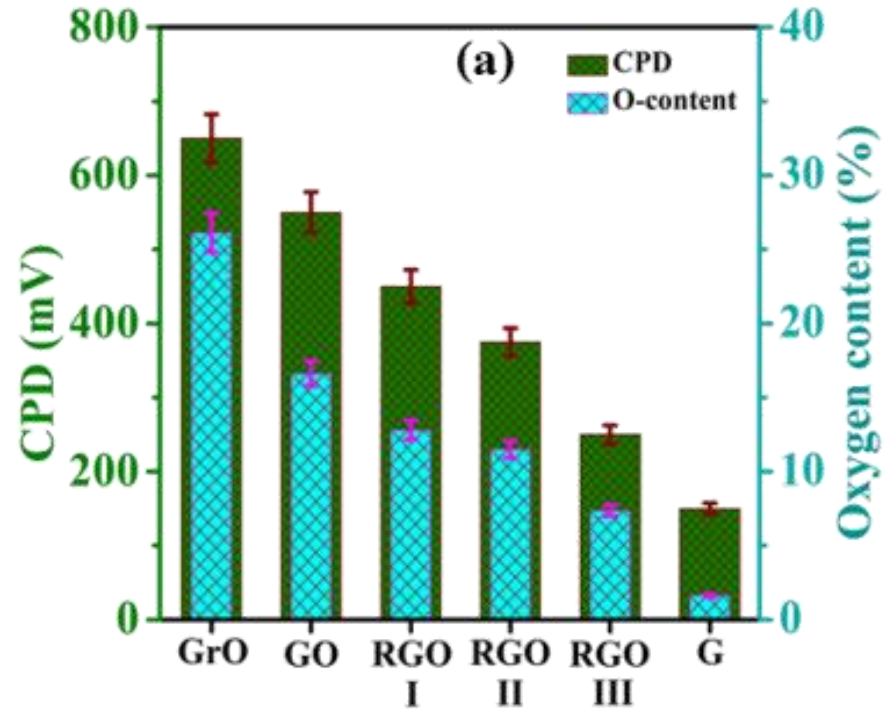
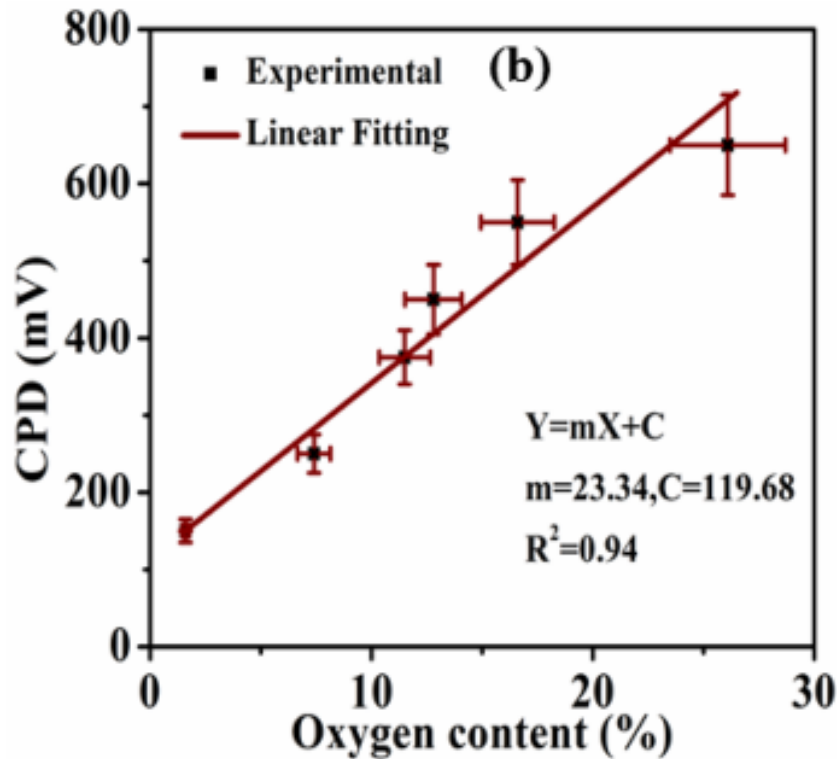
SWCNT: Single-Walled Carbon Nano Tube

EDAX: Energy dispersive X-ray spectroscopy

Table I: Carbon and Oxygen concentration (%) determined from EDAX studies.

	Graphite (Gr)	Graphite oxide (Gr O)	Graphene oxide (GO)	Reduced Graphene oxide-I (RGO-I)	Reduced Graphene oxide-II (RGO-II)	Reduced Graphene oxide-III (RGO-III)	Graphene (G)
Carbon (%)	98.4	73.2	82.8	86.6	87.9	92.0	98.1
Oxygen (%)	1.5	26.1	16.6	12.8	11.5	7.4	1.6





Relative surface contact potential difference (CPD) measurement between two different surfaces following the relation:

$$V_{\text{CPD}} = \frac{(\Phi_{\text{tip}} - \Phi_{\text{sample}})}{e}$$

Here, Φ denotes work function, and e is the elementary charge of electron.

Using Au tip: $\Phi_{\text{tip}} = 5.1 \text{ eV}$

Field effect transistor type gas sensors

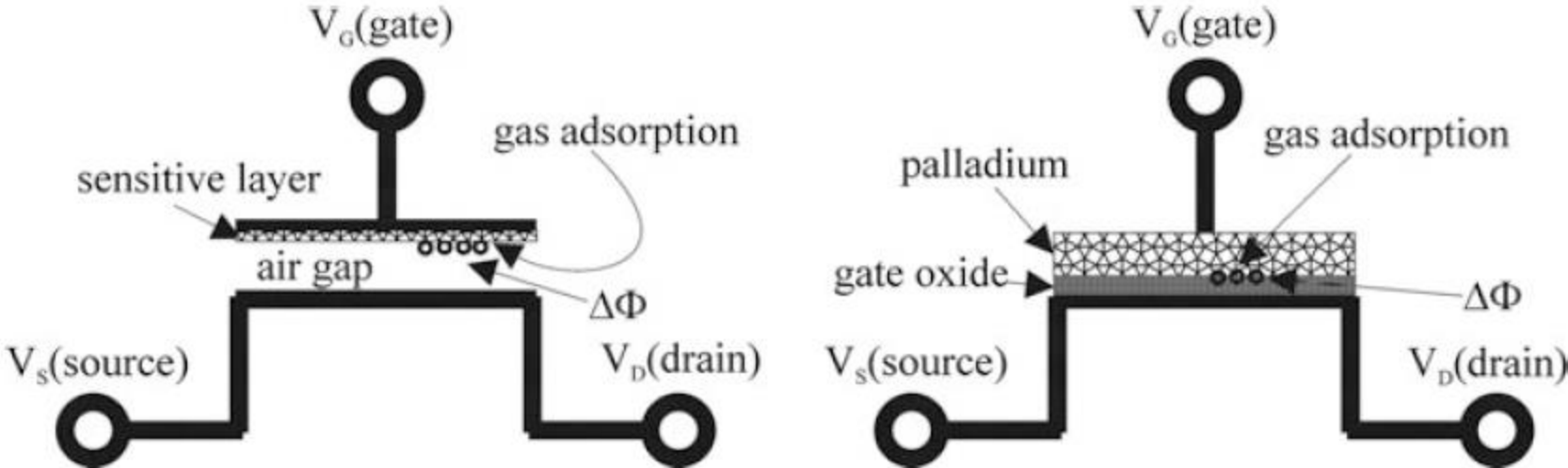
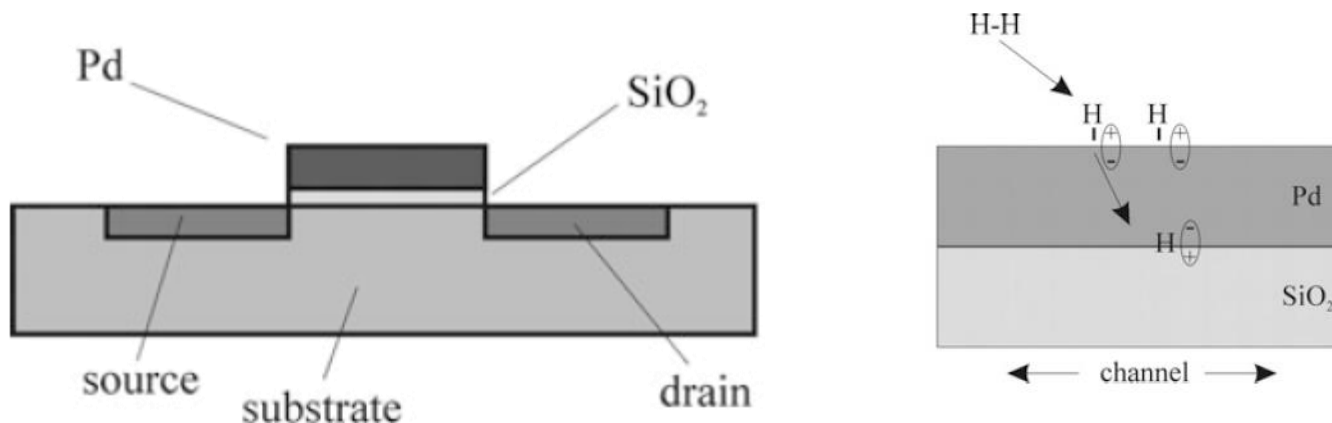


Fig. 2 Schematic view of an SG-FET (left) and a Lundström-FET (right)

Suspended gate field effect transistor gas sensors (SG-FET) belong to solid state gas sensors. In principle, they are capable of detecting a wide range of different gases by simply exchanging chemical-sensitive adsorption layers. This adsorption leads to a change in work function of the sensitive layer.

Lundström developed the first gas sensor based on a conventional FET in 1975.



$$I_{DS} = \mu \frac{W_{\text{eff}}}{L_{\text{eff}}} C_I \left(V_G + \frac{\Delta\Phi}{e} - V_T \right) V_{DS}.$$

Here, μ denotes the carrier mobility; W_{eff} and L_{eff} are the effective channel dimensions of the transistor; e is the elementary charge; C_I is the oxide capacitance with respect to the area; and V_G and V_{DS} are the applied gate and source–drain voltages.

In summary. This FET has been proven to be a reliable sensor for hydrogen concentrations up to 1.5%.

Lundström developed the first gas sensor based on a conventional FET in 1975.

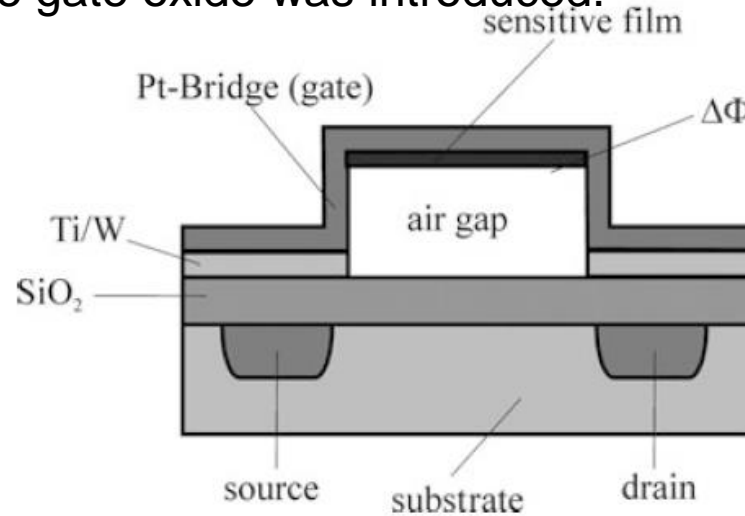
Lundstrom discovered that when the gate was made of a thin layer of palladium, the atmospheric hydrogen would dissociate and diffuse through to the interface, creating a dipole layer and causing a shift in the threshold voltage. Using a circuit to drive a constant current through the device with common gate and drain terminals leads to a characteristic voltage response (equal to the shift in threshold voltage) of this type of device to hydrogen

$$\Delta V_{GDS} = \Delta V_T = \Delta V_{\max} \frac{k\sqrt{C_H}}{1 + k\sqrt{C_H}}$$

where k is a constant and C_H is the partial pressure of the hydrogen in air. The solid palladium gate has subsequently been replaced by an ultrathin discontinuous metal film so that larger, less diffuse, molecules can reach the oxide surface and be sensed.

Suspended gate field effect transistor gas sensors (SG-FET)

In order to abolish the disadvantages of Lundstrom-type gas sensors, which come along with the essential need of a permeable gate material, an air gap between the sensitive layer and the gate oxide was introduced.

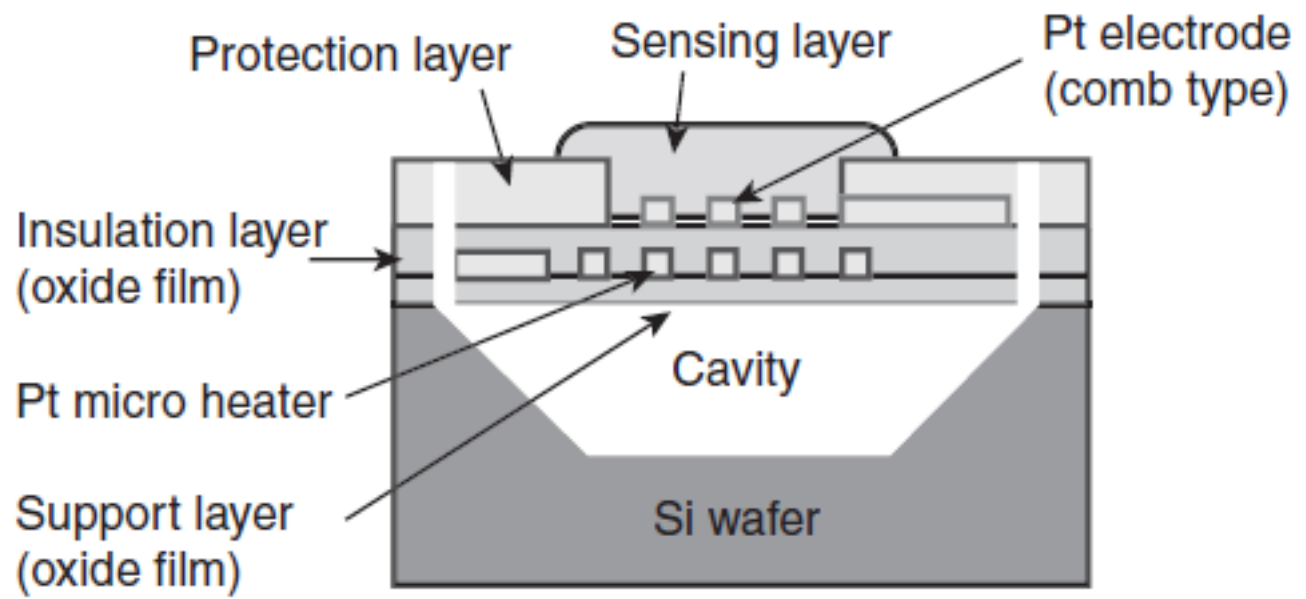


$$I_{DS} = \mu \frac{W_{\text{eff}}}{L_{\text{eff}}} C_{\text{eff}} \left(V_G + \frac{\Delta\Phi}{e} - V_T \right) V_{DS} \quad \text{with} \quad C_{\text{eff}} = \frac{C_I C_A}{C_I + C_A}. \quad (2)$$

Here, C_I denotes the gate oxide capacitance, and C_A is the capacitance of the air gap and the sensitive layer. Because of the large air gap, C_A is very small in comparison to C_I , so $C_{\text{eff}} \approx C_A$. Consequently, the threshold voltage V_T is increased and can reach values up to 100 V.

Suspended gate field effect transistor gas sensors (SG-FET)

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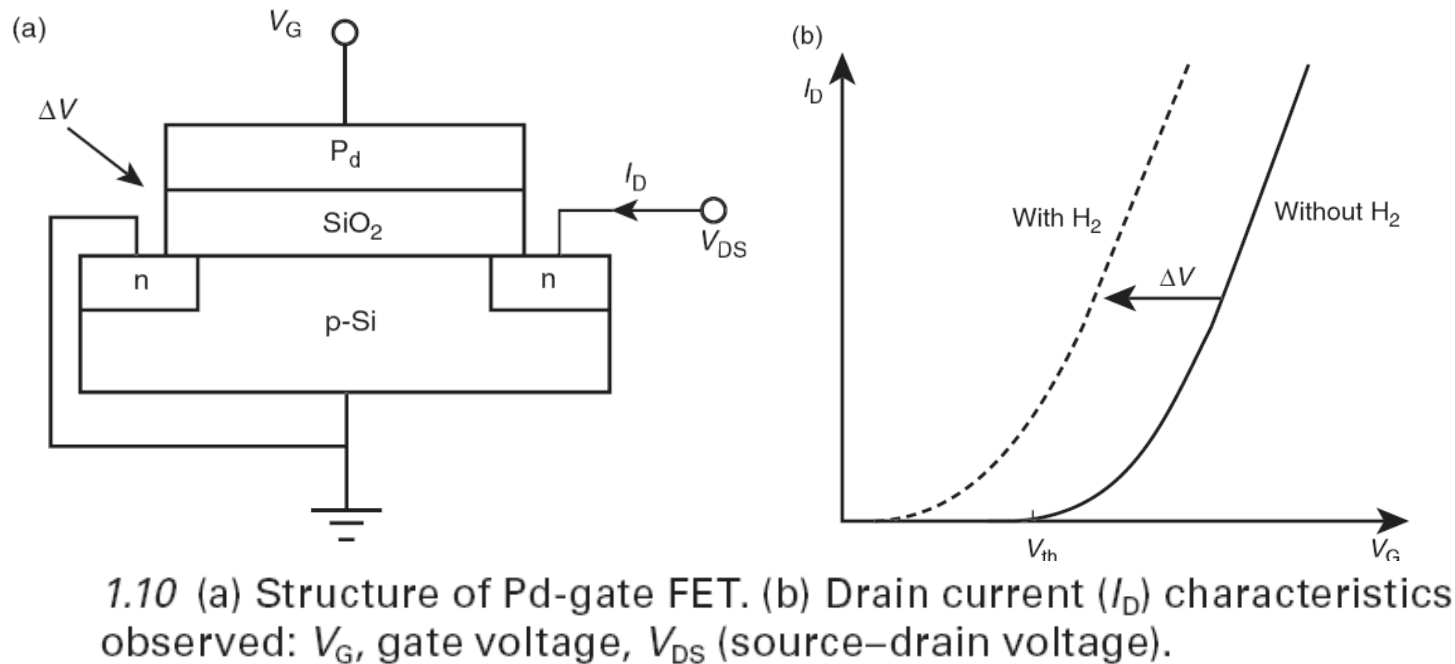


1.15 MEMS gas sensor.

Field effect transistor type gas sensors

Pd-gate FET gas sensors

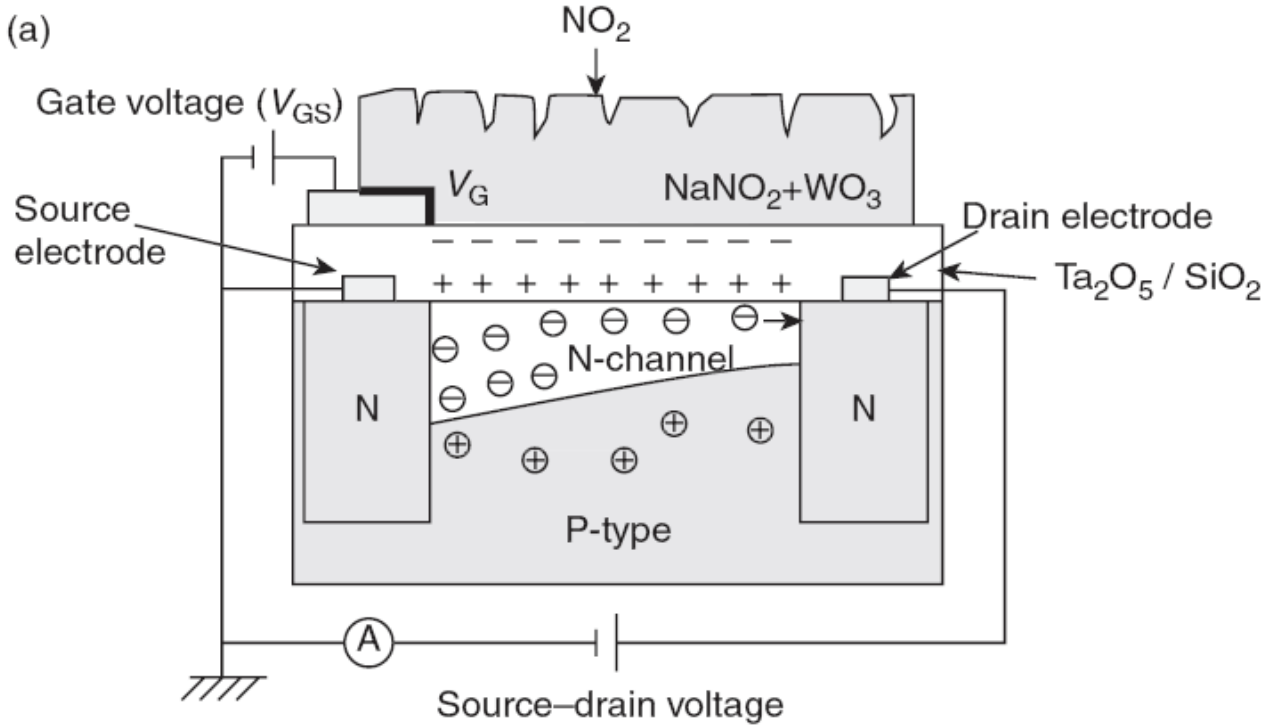
It responded to H₂ and NH₃ in air at 423 K. Reportedly, the H atoms dissociated from these molecules are dissolved into Pd metal and polarize in the vicinity of the border to the underlying insulator layer (SiO₂) to modulate the electrical field underneath.



Field effect transistor type gas sensors

Solid electrolyte-gate field effect transistor

NO_2 sensor can be fabricated by attaching NaNO_2 (Na^+ ionic conductor) and CO_2 sensor can be fabricated by Li_2CO_3 -based composite salt (Li^+ ionic conductor) attaching to the gate metal.



Construction of NaNO_2 -gate FET sensor.

Field effect transistor type gas sensors

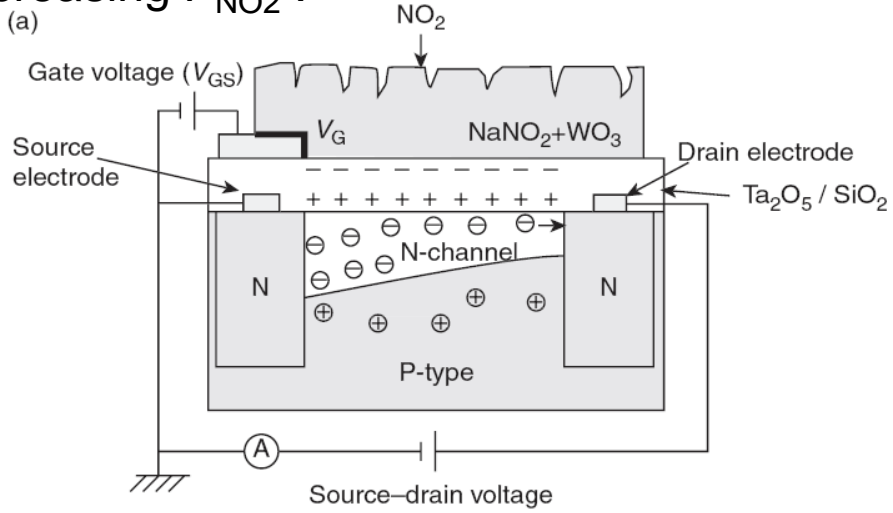
Solid electrolyte-gate field effect transistor

Three-phase contact between metal, solid electrolyte and gas is known to act as an active site for electrochemical reactions (half cell reaction).

$$\text{NO}_2 + e^- + \text{Na}^+ = \text{NaNO}_2, \Phi_M - \Phi_{SE} = \left(\frac{RT}{F} \right) \ln P_{\text{NO}_2} + \text{Constant}$$

The electrical potentials of metal and solid electrolyte are Φ_M and Φ_{SE} , respectively.

Φ_{SE} is raised higher than Φ_M , which is now controlled externally as gate voltage. This means that, at a fixed gate voltage, Φ_{SE} increases and, hence, the electrical field underneath also increases with increasing P_{NO_2} .



Field effect transistor type gas sensors

Oxide semiconductor-gate field effect transistor

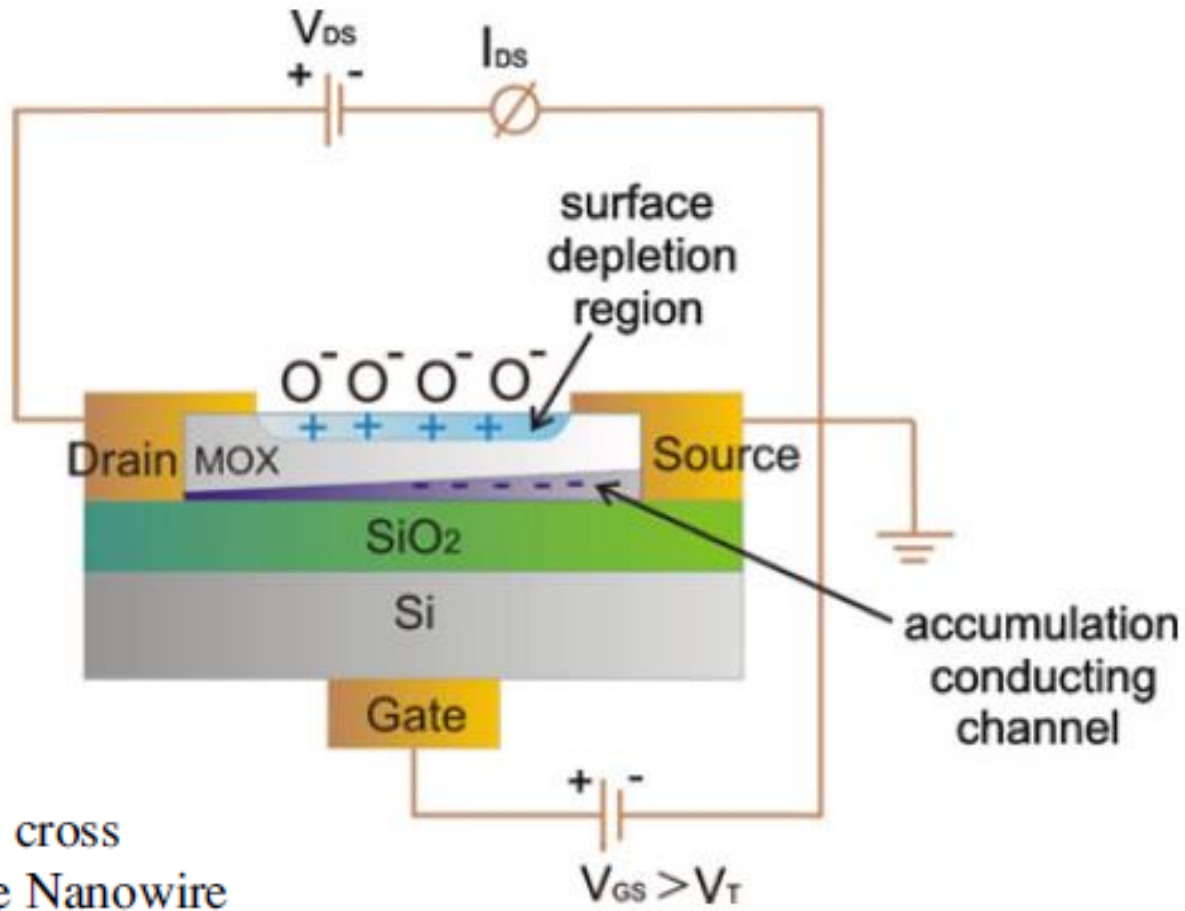


Fig. 8 Schematic cross section of a Single Nanowire n-type Transistor device in accumulation